

## Student Activity Guide

### *Exploring Factors Effecting Deposition, Morphology, and Thickness of Thin Metallic Layer of Copper*

**Purpose:** You will create thin layers of copper and nickel in an electrochemical reaction to understand how an electric current passed through an ionic solution will result in a chemical reaction which will separate materials. In addition you will also explore the various parameters effecting deposition, morphology, and thickness of the film to be deposited.

Nanotechnology is the science of the very small – atoms and molecules. Scientists and engineers are creating new materials and devices by using unique properties of nanoscale materials. Thin film layers are particularly important in nanotechnology and may have many applications including solar cells, fuel cells, and even DNA identification. You will be experimenting with variables that may or may not affect the deposition of thin films.

#### Make a Prediction

What variables do you think will have the most effect on the thickness and morphology of the copper film deposited in this experiment?

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#### Materials

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| <ul style="list-style-type: none"> <li>• Balance</li> <li>• Metal shears</li> <li>• Drying oven or heat lamo</li> <li>• AA batteries</li> <li>• Ruler</li> <li>• Acetone</li> <li>• Copper wires</li> <li>• Alligator clips</li> <li>• (2) 500mL beakers</li> <li>• 1 glass stirring rod</li> <li>• Magnetic stir bar and stirrer</li> <li>• Nickel foil</li> <li>• Forceps</li> </ul> | <ul style="list-style-type: none"> <li>• 100 mL graduated cylinder</li> <li>• Copper II Sulfate (anyhydrous)</li> <li>• 10% Nitric Acid</li> <li>• Cu foil (2)</li> <li>• Nail Polish</li> <li>• Connecting electrical wires</li> <li>• 1 large watch glass</li> <li>• 16oz soft drink bottle</li> <li>• Microscope</li> <li>• Spatula</li> <li>• Voltmeter</li> <li>• Sulfuric acid</li> <li>• Toothpick</li> <li>• Hammer</li> </ul> |
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## The Reaction

1. Once the parameters to be tested are known, secure a split wire and connect the split wires to both electrode posts on opposite sides of the foil post. Connect it to the positive end of the battery.
2. Record the time that the reaction began, and allow to run for 2 minutes (except those groups testing time)

## Copper Foil Processing

1. After the reaction has run for 2 minutes, disconnect the battery terminal wires to stop the reaction.
2. Carefully remove the nickel foil from the electrode chamber.
3. Remove the foil from the electrode post by sliding the copper wire away from the foil.
4. Rinse the nickel foil gently with distilled water.
5. Place the nickel foil in a clean beaker and dry for 10 minutes under a heat lamp or in a drying oven.
6. Once the foil is completely dry obtain the mass of the foil sample and record in the appropriate table.
7. Repeat this process with the four remaining strips.

## Microscopic observations

1. Describe the overall appearance of the deposited film, and make detailed notes of your observations.
2. Compare and contrast the surface of the plated copper to the other parameters tested.
3. Save a picture of your deposited layer using the computer connection to the microscope if (available).
4. How might an electron microscope allow one to study the sample more in depth.

## Cleanup:

1. Any discarded nitric acid should be placed in the designated acid disposal container.
2. Acetone rinse should not be placed in the sink, but in a bottle designated for organic waste disposal.
3. Excess copper sulfate solution should be placed into a container designated for inorganic waste.
4. Copper wire electrodes not used up in the reaction should be cleaned in nitric acid, rinsed with distilled water, and placed in a beaker to dry.





#### IV. Determining Thin Film Thickness

1. The height of the film will be equal to the difference in thickness of the copper foil before and after the reaction.
2. The volume and density equations will be used in tandem to determine the height of the foil post reaction.

#### Calculations

Height Before Reaction .0046cm                      mass nickel before = .62g

$$V_{\text{foil}} = l * w * h$$

$$D = m/v$$

$$l = 5 \text{ cm} \quad w = 3 \text{ cm}$$

$$V_{\text{foil}} = \text{mass} / \text{Density}_{\text{copper}}$$

$$h = V_{\text{foil}} / l * w$$

$$\text{mass} = .62\text{g} \quad \text{Density}_{\text{copper}} = 8.956 \text{ g/cm}^3$$

$$h = .06292\text{cm}^3 / 5\text{cm} * 3\text{cm}$$

$$V_{\text{foil}} = .62\text{g} / 8.956 \text{ g/cm}^3 = .0692 \text{ cm}^3$$

$$h = .0046\text{cm}$$

Height After Reaction .0067cm                      mass nickel after = .9g

$$V_{\text{foil}} = l * w * h$$

$$D = m/v$$

$$l = 5 \text{ cm} \quad w = 3 \text{ cm}$$

$$V_{\text{foil}} = \text{mass} / \text{Density}_{\text{nickel}}$$

$$h = V_{\text{foil}} / l * w$$

$$\text{mass} = .9\text{g} \quad \text{Density}_{\text{nickel}} = 8.956 \text{ g/cm}^3$$

$$h = .1005\text{cm}^3 / 5\text{cm} * 3\text{cm}$$

$$V_{\text{foil}} = .9\text{g} / 8.956 \text{ g/cm}^3 = .1005 \text{ cm}^3$$

$$h = .0067\text{cm}$$

Height of Thin Film = Height After Rxn – Height Before Rxn

$$= .0067 \text{ cm} - .0046 \text{ cm}$$

$$= .0021 \text{ cm, 21 micrometers}$$

## Analyze the Results

1. Did you observe what you predicted?

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If not, how did your observation differ from your prediction?

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2. What technologies do thin films stand to revolutionize?

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3. Which electrode served as the cathode in the electrolysis chamber?

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4. Which electrode served as the anode in the electrolysis chamber?

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5. Why might intermittent voltage affect deposition thickness and morphology?

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6. Why might solution acidity affect deposition thickness and morphology?

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7. How might the use of a scanning electron microscope (SEM) improve analysis of the deposited copper film?

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